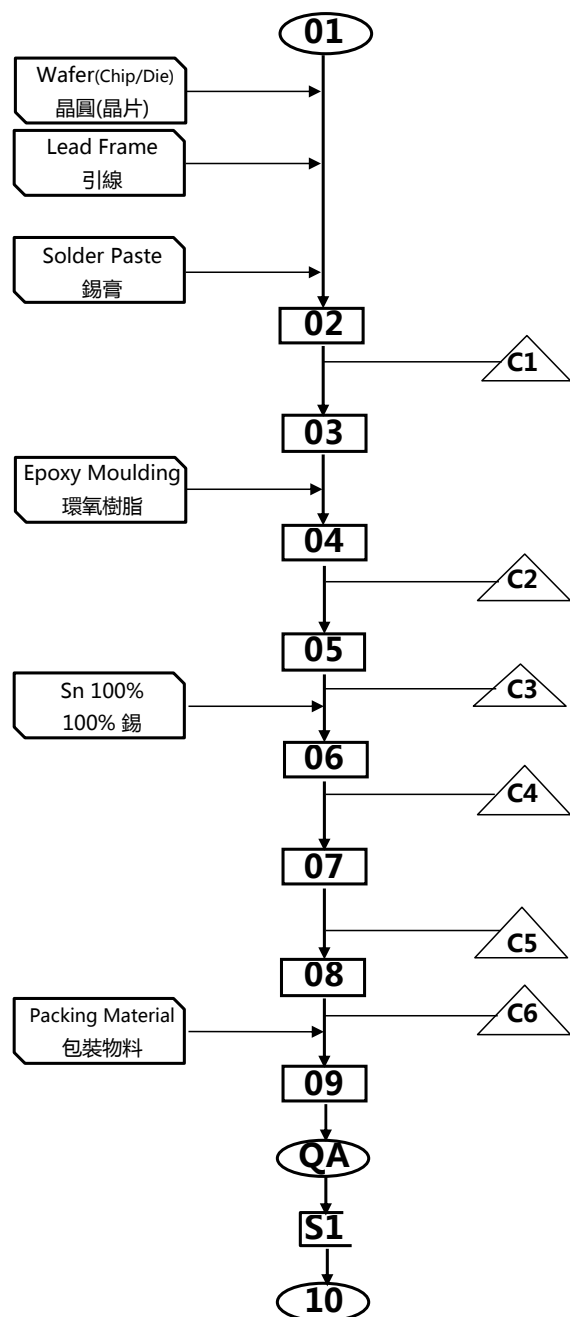


DIODES DIE ASSEMBLING 二極管晶片組裝

PROCESS FLOW CHART FOR CLIP BONDING PROCESS PRODUCTS
倒裝焊接工藝產品工序流程圖 (SOD123FL/HE, SOD323HE, CFP15, LBF)

PROCESS DESCRIPTION

流程說明：

01	MATERIAL INCOMING INSPECTION 來料檢查
02	DIE ASSEMBLING 晶片裝配
03	DIE SINTERING 晶片固定 (燒結焊接)
04	MOULDING 注塑
05	TRIMMING 修剪水口
06	SURFACE FABRICATION 表面加工
07	CUTTING & FORMING 切割及成型
08	100% ELECTRICAL TESTING, LASER MARKING & TAPING 100% 電性測試、激光法標記及上帶
09	PACKING 包裝
10	FINAL INSPECTION BEFORE DISPATCHING 交貨前最終檢查
QA	QUALITY ASSURANCE 品質保證檢查
S1	STORAGE 倉儲
C1	QUALITY MONITORING AND CONTROL(IPQC) OF DIE SINTERING 晶片燒結過程品質監測及控制
C2	QUALITY MONITORING AND CONTROL(IPQC) OF MOULDING 注塑過程品質監測及控制
C3	QUALITY MONITORING AND CONTROL(IPQC) OF TRIMMING 修剪水口過程品質監測及控制
C4	QUALITY INSPECTION AND CONTROL OF SURFACE FABRICATION 表面加工品質檢查及控制
C5	QUALITY MONITORING AND CONTROL(IPQC) OF CUTTING & FORMING 切割及成型過程品質監測及控制
C6	QUALITY MONITORING AND CONTROL(IPQC) OF TESTING, MARKING & TAPING 測試、標記及上帶過程品質監測及控制

	Operation 操作		Inspection 檢查
	Storage 儲存		Material 材料
	Quality Monitoring and Control 品質監測及控制		Outsourcing Process 外包工序